

Title (en)

A method for plating a copper interconnection circuit on the surface of a plastic device

Title (de)

Verfahren zur Plattierung einer Kupferverbindungsschaltung auf der Oberfläche einer Kunststoffvorrichtung

Title (fr)

Procédé de placage d'un circuit d'interconnexion au cuivre sur la surface d'un dispositif en plastique

Publication

EP 2267184 A1 20101229 (EN)

Application

EP 09163423 A 20090622

Priority

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Abstract (en)

There is disclosed a method for plating a copper interconnection circuit on the surface of a plastic device. The method comprises a step of depositing an activation layer on the outer surface of the plastic device and a step of plating with copper the outer surface of the plastic device, the activation layer activating plating where copper is needed. The method comprises a step of laser structuring the outer surface of the plastic device, in order to remove the activation layer locally where copper is not needed. Application : highly integrated electronics

IPC 8 full level

C23C 18/30 (2006.01); **C23C 18/20** (2006.01)

CPC (source: EP)

C23C 18/204 (2013.01); **C23C 18/30** (2013.01)

Citation (applicant)

- E.BEYNE ET AL.: "The polymer stud grid array package", PROC. IEPS, 30 September 1996 (1996-09-30)
- W.FALINSKI ET AL.: "Laser structuring of fine line printed circuit boards", 28TH SPRING SEMINAR ON ELECTRONICS TECHNOLOGY, pages 182 - 187

Citation (search report)

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